

SOLID ASSEMBLY OF FLIP-CHIP PACKAGE ATTACHED TO HEAT REMOVAL DEVICE AND METHOD OF MANUFACTURING SAME

Abstract

A flip-chip package assembly having a package substrate having a mounting surface to which a semiconductor die and a heat removal device is selectively mounted is provided. The flip-chip assembly is made out of a package substrate on which a semiconductor die is positioned and a heat removal device which is physically secured to the package substrate. The semiconductor die is thermally connected to the heat removal device through a thermal interface material. Further, a method for manufacturing the flip-chip package described herein is disclosed.

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